IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				under both lev	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Pistribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mi	ials and Mfg Information					
Supplier Inforn	nation																
Company name* Company unique II				ique ID	ue ID Uni			Unique ID Authority					Response Date*				
onsemi													2024-05-16				
Contact Name			Title - Contact			F	Phone - Contact*					Email - 0	Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com						
				Fitle - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com						
Requeste	ter Item Number Mfr Item		Number			Effective Da	ate Ve	Version M		Manufacturing Site		Veight	<u>t</u> *	UOM	Unit Type		
		NCP1618CDR2G NCP1618C (mu NCP1618)			ti mode) PFC (meta	al tweak	2024-05-16 P		PH1		7	4.52		mg	Each		
Ianufacturing	Proccess Informati	on															
Terminal	Plating / Grid Array Material		Γerminal Base Alloy J-S		J-STD-020 MSL R	20 MSL Rating		Peak Process Body Temperature		re Max Time at Peak Temper		Temperati	nture Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С		30 seco		ds 3	3			
Comments																	
evel 1 - maximum t	ime at peak temperatur	e during sol	ldering is 10-3	0 seconds	·				<u> </u>								
or more informati	on regarding material c	omposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.26	mg	Supplier	Silicon (Si)	7440-21-3		1.26	mg
Die Attach	0.37	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.074	mg
			Supplier	Silver (Ag)	7440-22-4		0.296	mg
Lead Frame	21.32	mg	Supplier	Silver (Ag)	7440-22-4		0.3624	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0256	mg
			Supplier	Iron (Fe)	7439-89-6		0.501	mg
			Supplier	Copper (Cu)	7440-50-8		20.4246	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0064	mg
Mold Compound-Black	50.28	mg		Epoxy resin	proprietary data		2.514	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0056	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1.257	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2514	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		45.252	mg
Plating	1.14	mg	Supplier	Palladium (Pd)	7440-05-3		0.0798	mg
			В	Nickel (Ni)	7440-02-0		1.0374	mg
			Supplier	Gold (Au)	7440-57-5		0.0228	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg